

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

### Title of Invention

SEMICONDUCTOR PACKAGE, METHOD OF  
MANUFACTURING THE SAME, AND SEMICONDUCTOR DEVICE

Application Number :

Confirmation Number:

First Named Applicant: Takahiro IJIMA

Attorney Docket Number: 021083a

Art Unit:

Examiner:

Search string: ( 5796587 ).pn

### US Patent Documents

**Note: Applicant is not required to submit a paper copy of cited US Patent Documents**

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
AR	1	5796587	1998-08-18	Lauffer et al.		361	763

### Signature

Examiner Name	Date
AR	12/08/04



<b>INFORMATION DISCLOSURE CITATION PTO-1449</b>	Atty. Docket No. 021083A	Serial No. 10/709,912
	Applicant(s): IIJIMA, Takahiro, et al.	
	Filing Date: June 4, 2004	Group Art Unit: 2829

### U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Name	Date	Class	Subclass	Filing Date (If appropriate)
_____	AA					
_____	AB					
_____	AC					
_____	AD					
_____	AE					

### FOREIGN PATENT DOCUMENTS

Document No.	Date	Country	Translation (Yes or No)
_____	AF		
_____	AG		
_____	AH		
_____	AI		
_____	AJ		

### OTHER DOCUMENTS

<u>NR</u>	AK	Nakamura et al.; "POLYIMIDE FILMS PREPARED BY ELECTROPHORETIC DEPOSITION AND THEIR DIELECTRIC BREAKDOWN", SPIE, Volume 2780, pages 71-75, September 11-14, 1995.	
_____	AL		
Examiner	<u>NR</u>	Date Considered	<u>12/08/04</u>